

AF 2800

# AMENDMENT TRANSMITTAL LETTER

Docket No.  
M4065.0127/P127-A

Application No.  
99/660,324-Conf. #2581

Filing Date  
September 12, 2000

Examiner  
F. Toledo

Art Unit  
2581

Applicant(s): Kie Y. Ahn, et al.

Invention: SILICON MULTI-CHIP MODULE PACKAGING WITH INTEGRATED PASSIVE COMPONENTS AND METHOD OF MAKING

## TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	35	- 35 =		x	0.00
Independent Claims	1	- 3 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					

☒ Large Entity

☐ Small Entity

☐ No additional fee is required for this amendment.

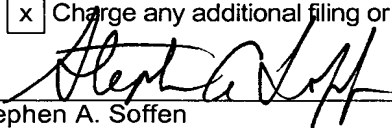
☐ Please charge Deposit Account No. \_\_\_\_\_ in the amount of, \$ \_\_\_\_\_  
A duplicate copy of this sheet is enclosed.

☐ A check in the amount of \$ \_\_\_\_\_ to cover the filing fee is enclosed.

☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. 04-1073  
as described below. A duplicate copy of this sheet is enclosed.

☒ Credit any overpayment.

☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.

  
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Dated: April 23, 2002

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